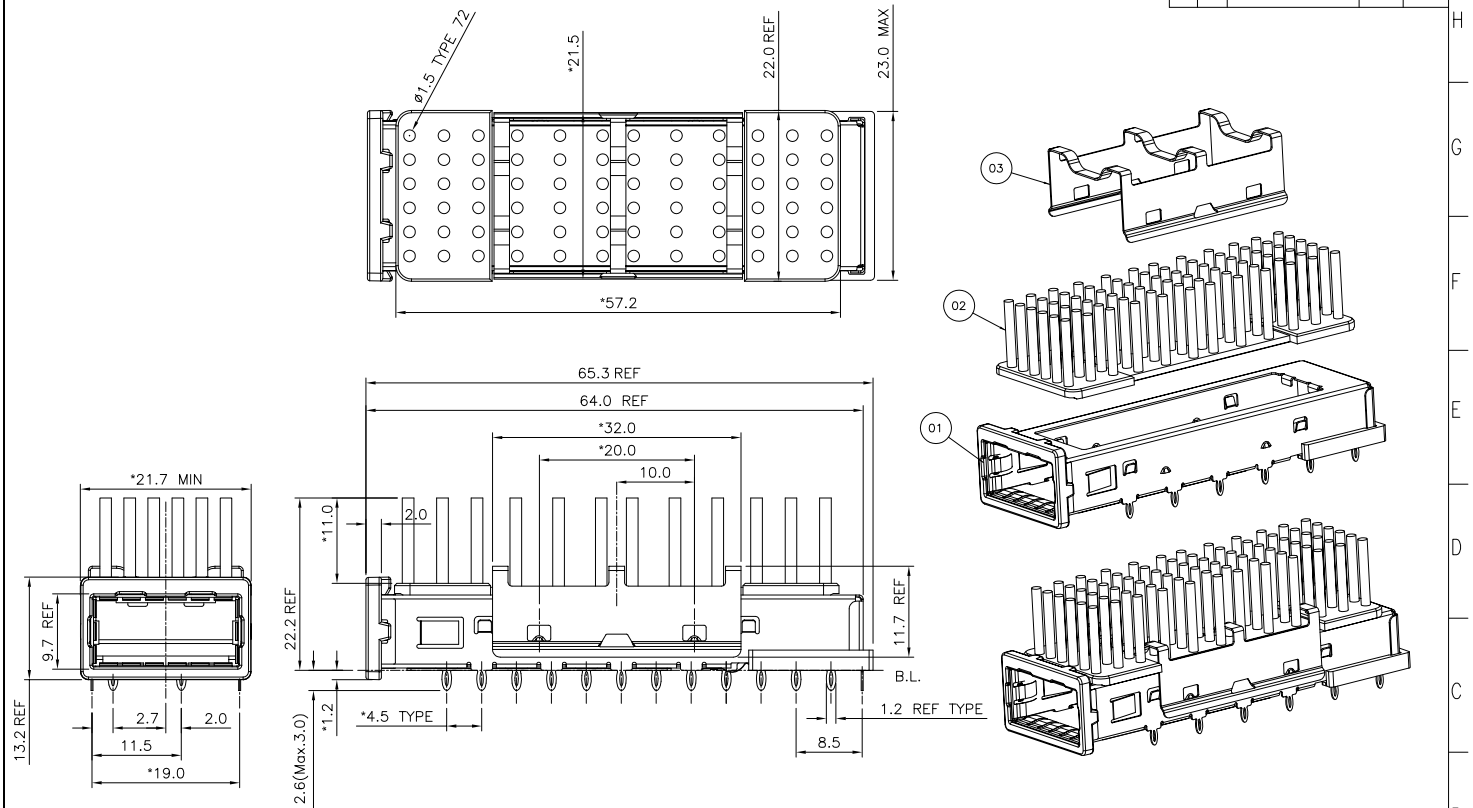


A1RFRD10

REVISION RECORD				
REV	ECC	DESCRIPTION	DRFT	CHKD



PART NUMBER: XFP003-L

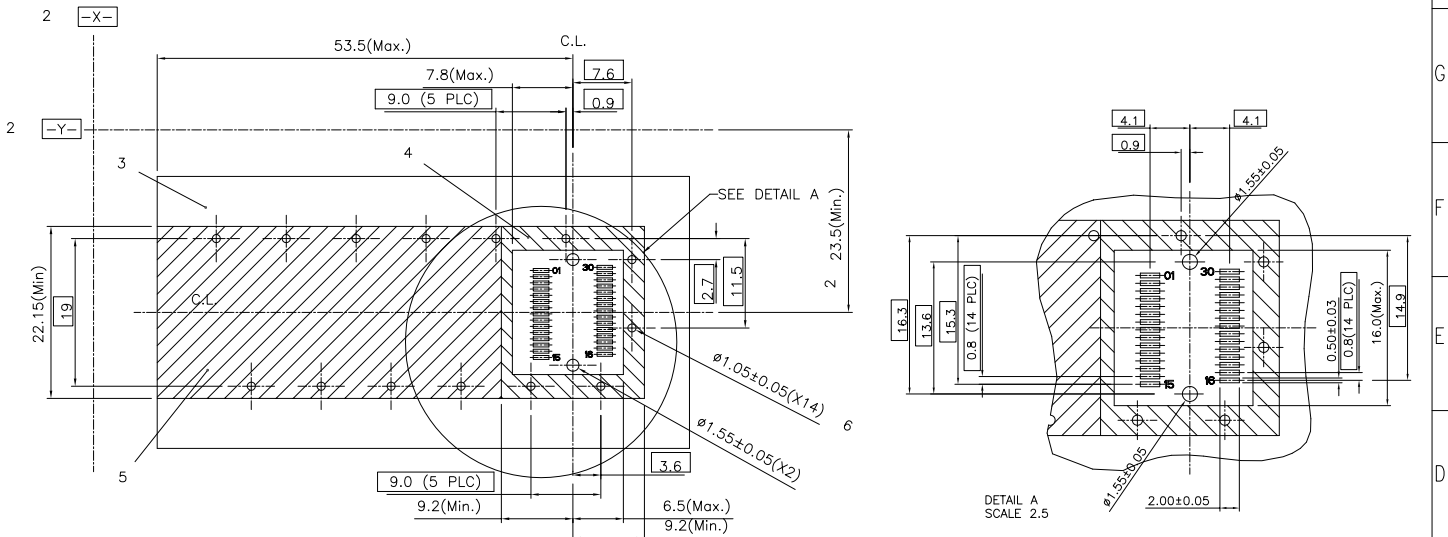
No.	DESCRIPTION	Q'ty	MATERIAL	PLATING	REMARK
01	XFP CAGE ASSEMBLY (Non-Logo)	1			
02	XFP HEAT SINK (11.00mm)	1	AL	Ni	
03	XFP HEAT SINK CLIP	1	SUS		

<table border="1"> <tr> <td>MM (INCH)</td> <td>DFTO tzou</td> <td>DATE 06/02/06</td> </tr> <tr> <td>TOLERANCES EXCEPT AS NOTED</td> <td>CHKD</td> <td>DATE</td> </tr> <tr> <td></td> <td>INFO</td> <td>DATE</td> </tr> <tr> <td></td> <td>APP'VL</td> <td>DATE</td> </tr> <tr> <td></td> <td>MATERIAL :</td> <td></td> </tr> <tr> <td></td> <td>QTY :</td> <td></td> </tr> <tr> <td></td> <td>FINISH :</td> <td></td> </tr> <tr> <td></td> <td>SCALE :</td> <td>1 : 2</td> </tr> </table>	MM (INCH)	DFTO tzou	DATE 06/02/06	TOLERANCES EXCEPT AS NOTED	CHKD	DATE		INFO	DATE		APP'VL	DATE		MATERIAL :			QTY :			FINISH :			SCALE :	1 : 2	<p>FULL RISE ELECTRONIC CO., LTD</p> <p>(Non-Logo)</p> <p>TITLE XFP CAGE WITH PCI HEAT SINK KIT</p> <p>DRAWING NO. XFP003-L SIZE REV /PART NO. SEE NOTE A3 0</p> <p>DO NOT SCALE DRAWING SHEET 1 OF 2</p>
MM (INCH)	DFTO tzou	DATE 06/02/06																							
TOLERANCES EXCEPT AS NOTED	CHKD	DATE																							
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	FINISH :																								
	SCALE :	1 : 2																							

8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

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REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



RECOMMEND P.C.B. LAYOUT

Note:

- DESIGN MEETS REQUIREMENTS OF XFPMSA SPECIFICATION REV. 3.1 (10 GIGABIT SMALL FROM FACTOR PLUGGABLE MODULE).
- DATUM $\boxed{-X-}$ AND $\boxed{-Y-}$ ESTABLISHED BY CUSTOMER.
- DATUM $\boxed{-A-}$ IS TOP SURFACE OF HOST BOARD.
- INDICATED SURFACES TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND.
- CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)
- RECOMMENDATION FOR P.C.B. BOARD HOLES:
 A. HOLE ϕ AFTER DRILLING : 1.15 ± 0.02 mm.
 B. HOLE ϕ Sn PLATE : 1.05 ± 0.05 mm.
 C. $25\mu\text{m} \sim 50\mu\text{m}$ COPPER UNDERPLATE.
- CAUTION- REFLOW PROCESS WILL DAMAGE CAGE ASSEMBLY.

TOLERANCES EXCEPT AS NOTED .0 ± 0.2 ± .00 ± 0.15 ± .000 ± 0.075 ±		DFTO lzou DATE 06/02/06 CHKD DATE MFO DATE APPVL DATE	FULL RISE ELECTRONIC CO., LTD (Non-Logo)	
ANGLES ± 0.5 		MATERIAL : QT'Y : FINISH :	TITLE XFP CAGE WITH PCI HEAT SINK KIT	
THIRD ANGLE PROJECTION		SCALE : 1 : 2	DRAWING NO. XFP003-L /PART NO. SEE NOTE	SIZE REV A3 0
DO NOT SCALE DRAWING			SHEET 2 OF 2	A

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